

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT | |
| NATURE OF CONVEYANCE: | ASSIGNMENT | |
| CONVEYING PARTY DATA | | |
| | Name | Execution Date |
| | DARIN DUNG NGUYEN | 07/08/2011 |
| RECEIVING PARTY DATA | | |
| Name: | FUJITSU SEMICONDUCTOR LIMITED | |
| Street Address: | 2-10-23 SHIN YOKOHAMA | |
| Internal Address: | KOHOKU-KU, YOKOHAMA-SHI | |
| City: | KANAGAWA | |
| State/Country: | JAPAN | |
| Postal Code: | 222-0033 | |
| PROPERTY NUMBERS Total: 1 | | |
| | Property Type | Number |
| | Application Number: | 13971025 |
| CORRESPONDENCE DATA | | |
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| ATTORNEY DOCKET NUMBER: | FUJITSU - G01198 | |
| NAME OF SUBMITTER: | JENNY KATHMAN | |
| SIGNATURE: | /Jenny Kathman/ | |
| DATE SIGNED: | 03/17/2014 | |
| Total Attachments: 2 | | |
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| source=Executed Assignment 1_Active_15226019_1#page2.tif | | |

ASSIGNMENT

WHEREAS, I, the undersigned sole inventor, of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, said application having been executed on the date set forth below; and

WHEREAS, Fujitsu Semiconductor Limited (hereinafter referred to as "Assignee"), with an address of 2-10-23 Shin Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033, Japan, desires to acquire my entire rights, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for and in consideration of One United States Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, provisionals, reissues, continuations, continuations-in-part and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

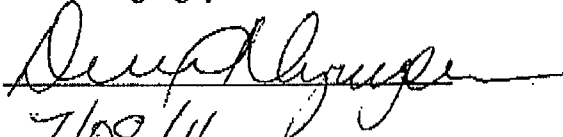
I will communicate to Assignee any facts known to me respecting any improvements; and, at the expense of Assignee, I will testify in any legal proceedings, sign all lawful papers, execute all divisional, provisionals, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

ATTORNEY DOCKET NO.
080699.0126

ASSIGNMENT

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|---------------------------------|--|
| Title of the Invention: | TEMPERATURE COMPENSATION CIRCUIT |
| Full name of inventor: | Darin Dung Nguyen |
| Inventor's signature |  |
| Date | 7/08/11 |
| Residence (City, County, State) | Phoenix, Maricopa County, Arizona 85042 |

AUS01:611207.1

RECORDED: 03/17/2014

PATENT
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